

ATTACHMENT A
Clean Replacement Claims

A clean copy of the amended claims is provided as follows:

Claims 2, 5, 20, 21, 22 and 36

2. (Once amended) A semiconductor laser module as defined in Claim 1, comprising an optical fiber optically coupled for receiving laser light emitted from the semiconductor laser element.
5. (Once amended) A semiconductor laser module as defined in Claim 3, comprising a surge suppression circuit for preventing surge current from flowing into said thermo module.
20. (Once amended) A semiconductor laser module as defined in Claim 16, comprising: a lensed optical fiber in which a lens is formed at a tip end portion onto which laser light is incident.
21. (Once amended) A semiconductor laser module as set forth in Claim 1 comprising:
 - a package having a through hole communicating from the inside of the package to the outside thereof for accommodating the semiconductor laser element and the thermo-module;
 - an optical fiber supporting member disposed within the through hole; wherein an end portion side of an optical fiber is for being introduced from the outside of said package into the inside thereof via a through hole provided in said optical fiber supporting member, and wherein a first substrate is thermally isolated from said optical fiber supporting member.
22. (Once amended) A semiconductor laser module as defined in Claim 21, comprising a lensed optical fiber in which a lens is formed at a tip end portion onto which laser light is incident.
36. (New) A semiconductor laser module as defined in Claim 5, wherein the surge suppression circuit comprises a diode disposed in series with said thermo module.